

IN THE CLAIMS:

Kindly amend claim 1, as follows:

1. (Currently Amended) A method for forming a solder bonded sputter target/backing plate assembly comprising the steps of:

a) forming a continuous solid backing plate with a bonding surface having at least two spaced-apart peripheral flanged segments disposed on the bonding surface of the backing plate;

b) forming a sputter target having a sputter surface and a bonding surface and at least two peripheral notched segments on the bonding surface, and said peripheral notched segments adapted for aligning with the peripheral flange segments;

c) applying a solder material to an [the] interface spacing defined by superimposing and aligning said bonding surface of the sputter target on the bonding surface of the backing plate and said peripheral flange segments having a height thickness larger than the depth thickness of the peripheral notched segments; and

d) allowing said solder material to solidify and bond the sputter target to the backing plate.

2. (Original) The method of claim 1 wherein the backing plate and sputter target are disc-shaped.

3. (Original) The method of claim 1 wherein the flange segments form a single arcuate-shaped flange and the notched segments form a single arcuate-shaped notch.

4. (Original) The method of claim 3 wherein the height of the flange is between about .100 inch and .500 inch.

5. (Original) The method of claim 3 where the thickness of the width of the flange is between about .100 inch and about .500 inch.

6. (Original) The method of claim 1 wherein the depth of the notch is between about .010 inch and about .030 inch.

7. (Original) The method of claim 3 wherein the difference in the height thickness of the flange is between about 5% and about 20% larger than the depth thickness of the notch.

8. (Original) The method of claim 3 forming the backing plate with at least one protruding ridge within the flange and on the bonding surface of the backing plate and said ridge having a width of between about .100 inch and about .500 inch.

9. (Original) The method of claim 8 wherein the at least one ridge on the bonding surface of the backing plate have a shape selected from the group comprising a circle, arcuate, square, rectangular, polygon and combination thereof.

10. (Original) The method of claim 1 wherein the sputter target is selected from the group comprising titanium, aluminum, copper, molybdenum, cobalt, chromium, ruthenium, rhodium, palladium, silver, osmium, iridium, platinum, gold, tungsten, silicon, tantalum, vanadium, nickel, iron, manganese, germanium, and alloys thereof and the backing plate is selected from the group comprising copper, aluminum, titanium, and alloys thereof and the backing plate is selected from the group comprising copper, aluminum, titanium, and alloys thereof.

Claims 11-20 (Cancelled).

REMARKS

Reconsideration of the subject matter in light of the amendments to claim 1 and the remarks which follow is respectfully requested. As correctly noted in